

FIG. 1

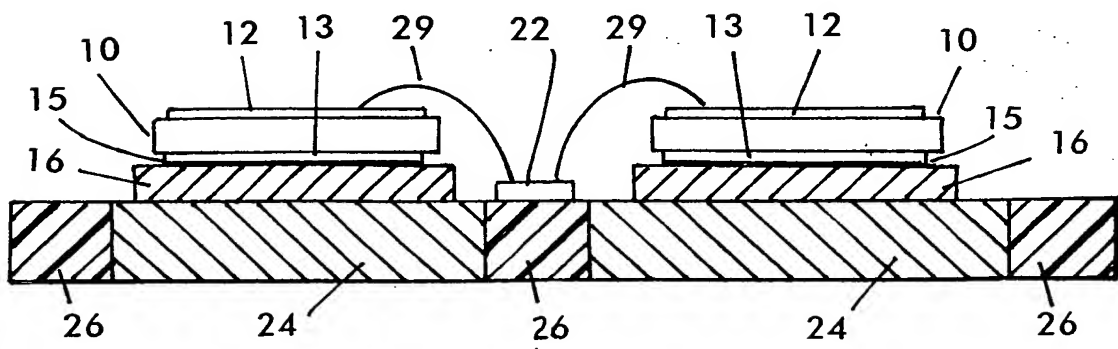


FIG. 2

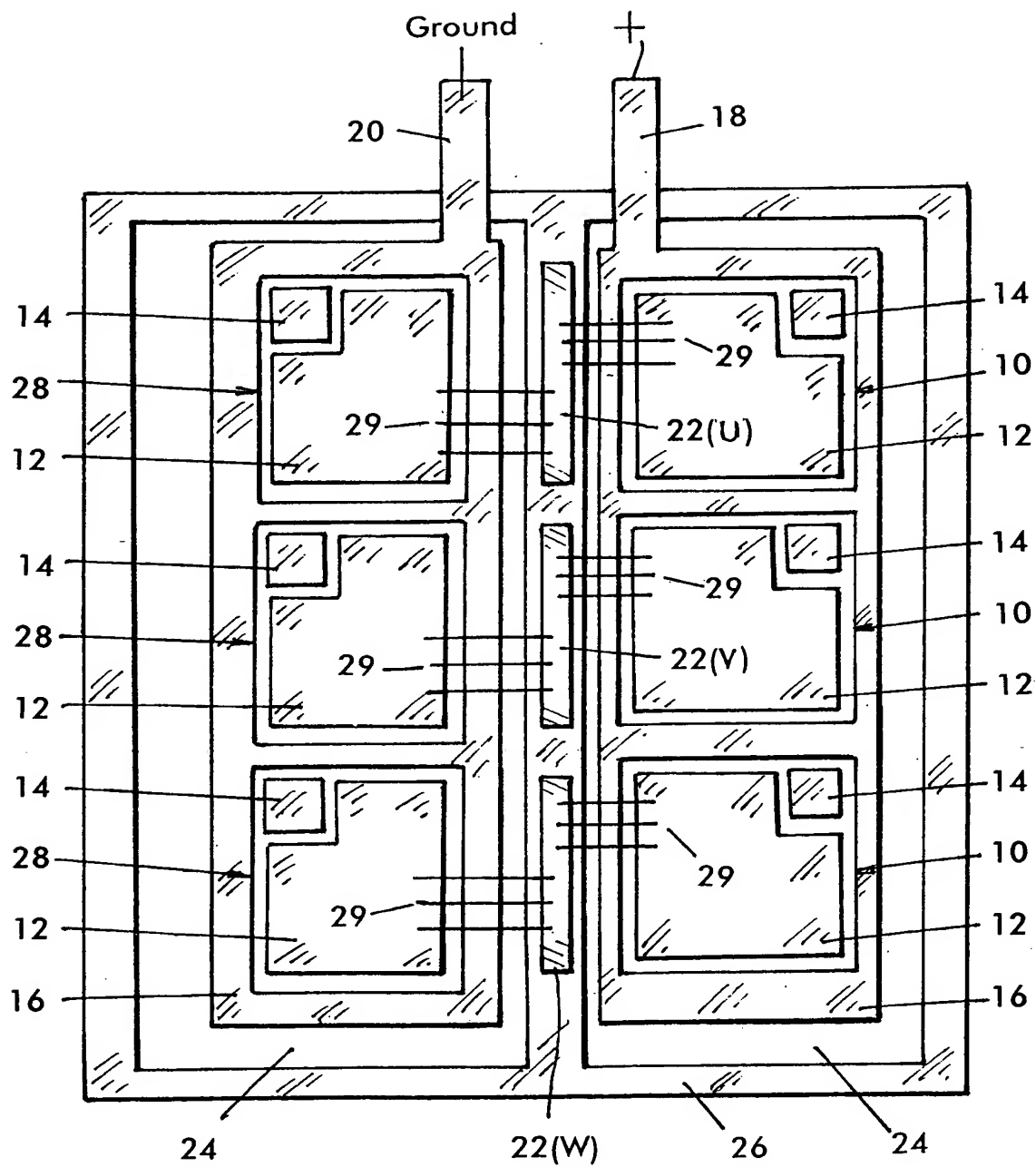


FIG. 3

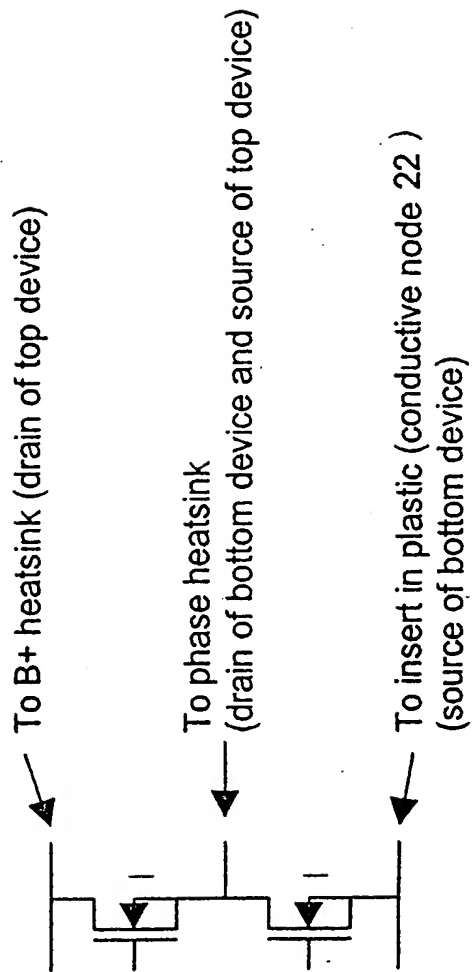


FIG. 4a

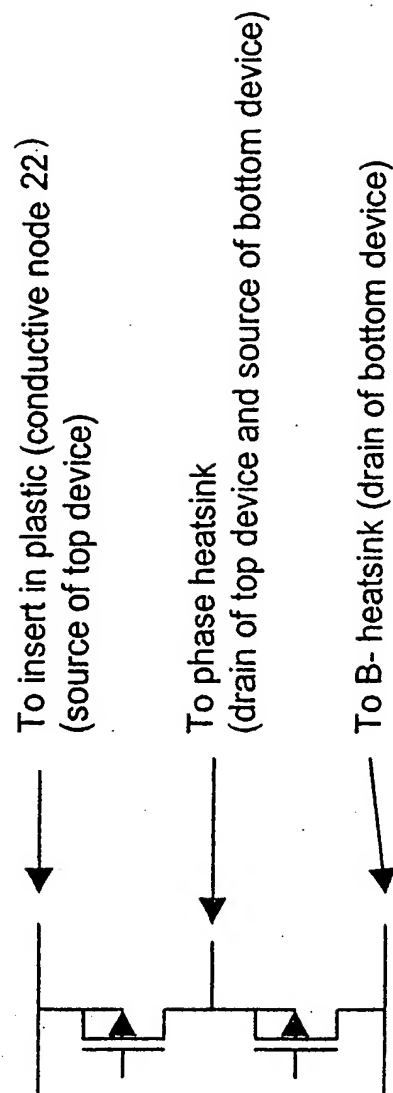


FIG. 4b



To insert in plastic (conductive node B+, similar to 22 of fig 3)

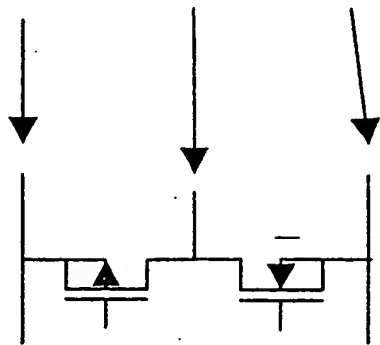


FIG. 4c

To B+ heatsink  
(drain of top device)

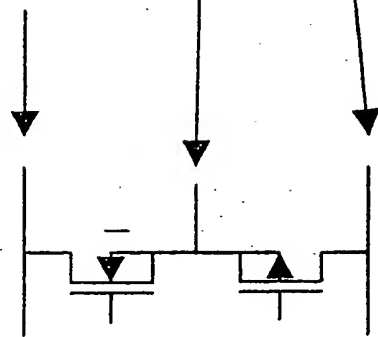
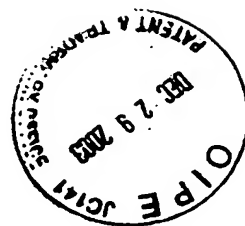
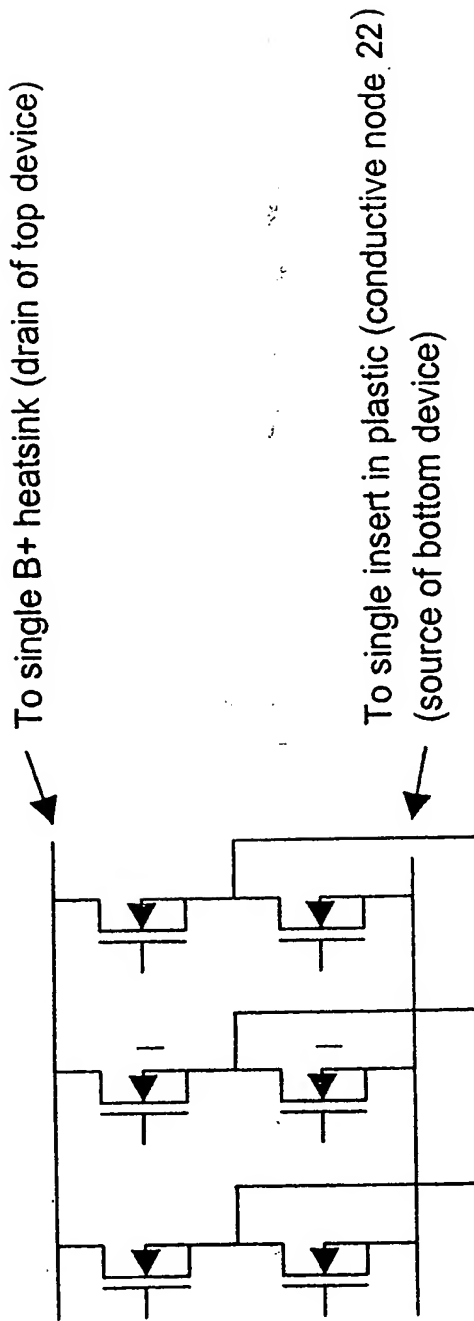
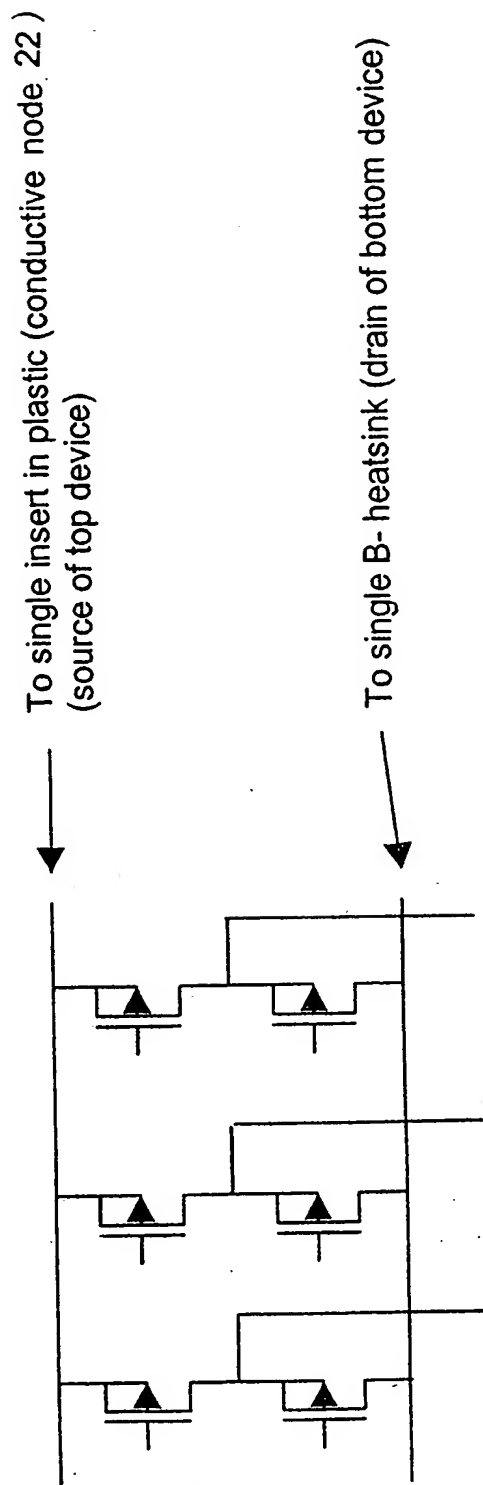


FIG. 4d





To phase heatsinks (3 heatsinks)  
(drain of bottom device and source of top device,



To phase heatsinks (3 heatsinks)  
(drain of top device and source of bottom device)

